

Organizational Chart

Europe | Japan | North America | China | Korea | Taiwan

**Last Updated: January 2020
v2**

Global Technical Committee (GTC) and Technical Committee (TC) Chapters



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	EH&S				TCC		TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committees

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committees

Note 1: An underlined Locale has an RSC and may also be referred as a “Region” (e.g., “Europe Region”)

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Traceability				TCC		TCC
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee

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Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles)

*In NA, Mircopatterining is traditionally called Microlithography



Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Micropatterning (Microlithography*)						TCC
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials		TCC	TCC	TCC		TCC	
HB-LED		TCC				TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”)

*In NA, Micropatterning is traditionally called Microlithography

**3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting
Vice-Chair: Frank Petzold – Trustsec



**Europe Chapter of Automation Technology
Global Technical Committee**

C: Christian Hoffmann – PEER Group

**Europe Chapter of Liquid Chemicals
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of Physical Interfaces & Carriers
Global Technical Committee**

C: Frank Petzold – Trustsec

**Europe Chapter of
Compound Semiconductor Materials
Global Technical Committee**

C: Arnd Weber – SiCrystal

**Europe Chapter of Information & Control
Global Technical Committee**

C: Frank Petzold – Trustsec

**Europe Chapter of PV Materials
Global Technical Committee**

C: Peter Wagner – Consultant
C: Christian Hagendorf – Fraunhofer CSP

**Europe Chapter of Gases
Global Technical Committee**

C: Jochen Ruth – Pall Corporation

**Europe Chapter of Metrics
Global Technical Committee**

C: Open

**Europe Chapter of Silicon Wafer
Global Technical Committee**

C: Werner Bergholz – International Standards Consulting
C: Peter Wagner – Consultant
C: Fritz Passek - Siltronic

SEMI Japan RSC Organization

Co-Chairs: Takayuki Nishimura – SCREEN Semiconductor Solutions, Hidetoshi Sakura – NuFlare Technology
Vice-Chair: Supika Mashiro – TEL

**Japan Chapter of
3D Packaging & Integration
Global Technical Committee**
C: Masahiro Tsuriya – iNEMI
C: Haruo Shimamoto – AIST
C: Kazunori Kato – AiT

**Japan Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of Liquid Chemicals
Global Technical Committee**
C: Hiroshi Tomita – KIOXIA
C: Hiroyuki Araki – SCREEN Semiconductor Solutions

**Japan Chapter of Silicon Wafer
Global Technical Committee**
C: Naoyuki Kawai – Meiji University
C: Tetsuya Nakai – SUMCO

**Japan Chapter of
Automation Technology
Global Technical Committee**
C: Terry Asakawa – Vistaideal Consulting
C: Fumiyasu Obuchi – SIEMENS
C: Yasuhiro Kaneko – YAMAHA Motor

**Japan Chapter of Gases
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**Japan Chapter of Metrics
Global Technical Committee**
C: Mitsune Sakamoto – ZAMA Consulting

**Japan Chapter of Traceability
Global Technical Committee**
C: Yoichi Iga – JEITA
C: Hirokazu Tsunobuchi – Nidec Sankyo

**Japan Chapter of
Compound Semiconductor Materials
Global Technical Committee**
C: Masayoshi Obara – Shin-Etsu Handotai

**Japan Chapter of
FPD Materials & Components
Global Technical Committee**
C: Tadahiro Furukawa – Yamagata University
C: Yoshihiko Shibahara – FUJIFILM

**Japan Chapter of Photovoltaic
Global Technical Committee**
C: Kazuhiko Kashima – Consultant
C: Masaaki Yamamichi – RTS Corporation

Special Groups
Reporting to the JRSC

**Japan Chapter of
Environmental Health & Safety
Global Technical Committee**
C: Supika Mashiro – TEL
C: Hidetoshi Sakura – NuFlare Technology
C: Moray Crawford – Hatsuta Seisakusho

**Japan Chapter of FPD Metrology
Global Technical Committee**
C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

**Japan Chapter of PV Materials
Global Technical Committee**
C: Kazuhiko Kashima – Consultant
C: Tetsuo Fukuda – Nihon University

**Standardization Process
Improvement (SPI)**
L: Supika Mashiro – TEL

**Japan Chapter of
Information & Control
Global Technical Committee**
C: Takayuki Nishimura – SCREEN Semiconductor Solutions
C: Mitsuhiro Matsuda – KOKUSAI ELECTRIC

**Japan Chapter of
Physical Interfaces & Carriers
Global Technical Committee**
C: Tsuyoshi Nagashima – Miraial
C: Noriyoshi Toyoda – Hirata Corporation
C: Daisuke Sado – Daihen

SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix



**NA Chapter of 3D Packaging & Integration
Global Technical Committee**

C: Sesh Ramaswami – Applied Materials
 C: Chris Moore – Covalent Metrology
 C: Bill Kerr – Evergreen Enhancement

**NA Chapter of Gases
Global Technical Committee**

C: Mohamed Saleem – Brooks Instrument

**NA Chapter of Metrics
Global Technical Committee**

C: David Bouldin – Fab Consulting
 C: Mark Frankfurth – Cymer
 C: Vladimir Kraz – BestESD

**NA Chapter of Silicon Wafer
Global Technical Committee**

C: Dinesh Gupta – STA
 C: Noel Poduje – SMS
 VC: Mike Goldstein

**NA Chapter of Automated Test Equipment
Global Technical Committee**

C: Mark Roos – Roos Instruments
 C: Stacey Ajouri – Texas Instruments

**NA Chapter of HB-LED
Global Technical Committee**

C: Mike Feng – Silian
 C: Chris Moore – Covalent Metrology
 C: Andrew Kim – InnovationforX

**NA Chapter of Microlithography
Global Technical Committee**

C: Bryan Barnes – NIST

**NA Chapter of Traceability
Global Technical Committee**

C: Yaw Obeng – NIST
 C: David Huntley – PDF Solutions

**NA Chapter of
Compound Semiconductor Materials
Global Technical Committee**

C: Russ Kremer – Freiberger Compound Materials
 C: James Oliver – Northrop Grumman

**NA Chapter of Information & Control
Global Technical Committee**

C: Jack Ghiselli – Ghiselli Consulting
 C: Brian Rubow – Cimetrix
 C: James Moyne – AMAT/ University of Michigan

**NA Chapter of Photovoltaic
Global Technical Committee**

C: James Moyne – AMAT/University of Michigan

**NA RSC
Technical Architect Board**

C: James Moyne – AMAT/ University of Michigan
 C: Yaw Obeng – NIST

**NA Chapter of
Environmental, Health & Safety
Global Technical Committee**

C: Chris Evanston – Salus Engineering
 C: Sean Larsen – Lam Research
 C: Bert Planting – ASML

**NA Chapter of Liquid Chemicals
Global Technical Committee**

C: Don Hadder – Intel
 C: Steve Rogers – KMG Chemicals
 C: Laura Ledenbach – PeroxyChem
 C: Koh Murai – Mega Fluid Systems

**NA Chapter of PV Materials
Global Technical Committee**

C: Hugh Gotts – Air Liquide

**NA Chapter of Facilities
Global Technical Committee**

C: Steve Lewis – BW Design Group

**NA Chapter of MEMS/NEMS
Global Technical Committee**

C: Steve Martell – Nordson SONOSCAN
 C: Michelle Bourke – Lam Research

**NA Chapter of
Physical Interfaces & Carriers
Global Technical Committee**

C: Matt Fuller – Entegris
 C: Melvin Jung – Intel

SEMI North America RSC Organization

China Locale

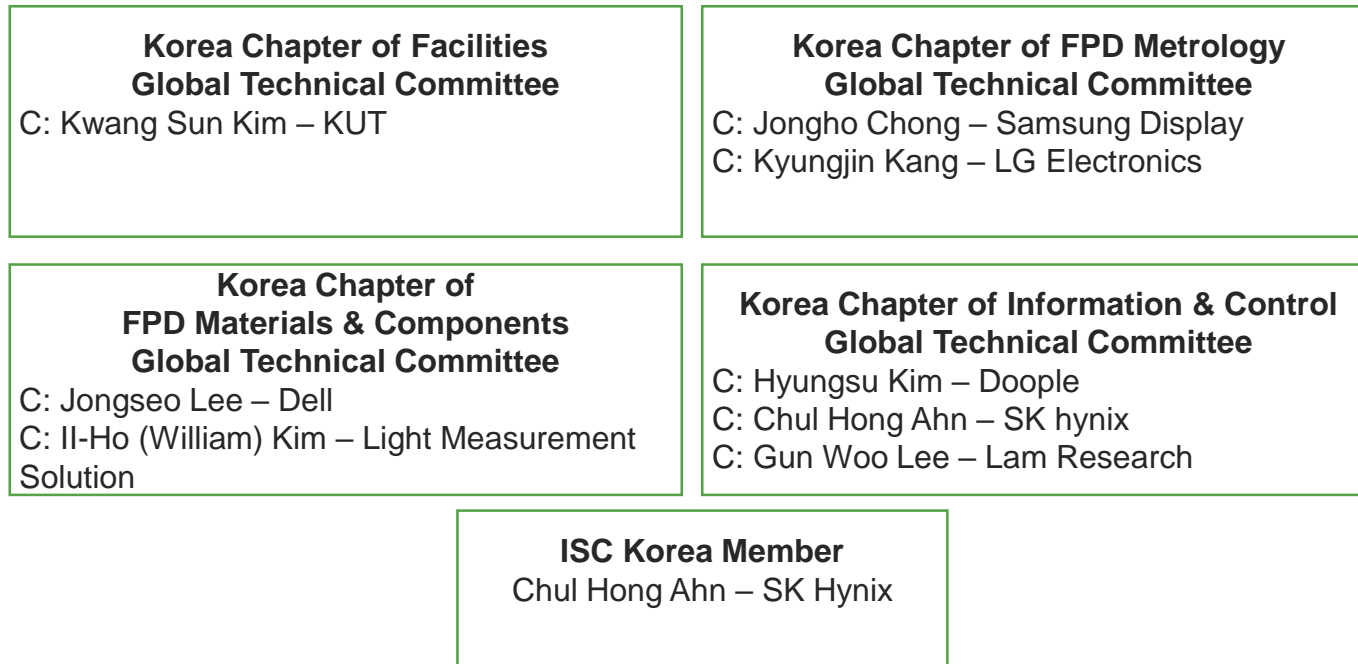
Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimatrix



SEMI North America RSC Organization

Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimetrix



SEMI North America RSC Organization

Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering
Vice-Chair: Brian Rubow – Cimatrix

**Taiwan Chapter of
3D Packaging & Integration
Global Technical Committee**

C: Wendy Chen – King Yuan Electronics
C: Chien-Chung Lin – ITRI
C: Roger Hwang – ASE

**Taiwan Chapter of
Environmental Health & Safety
Global Technical Committee**

C: Shuh-Woei Yu – SAHTECH

**Taiwan Chapter of Information & Control
Global Technical Committee**

C: Scott Yu – TSMC

**Taiwan Chapter of Automation Technology
Global Technical Committee**

C: K.C. Chou – ASE
C: Jen-Hui Tsai – ITRI
C: Gwo-Sheng Peng – ITRI/CMS
C: Jui-Ming Hua – MIRDC

**Taiwan Chapter of FPD Metrology
Global Technical Committee**

C: Jia-Ming Liu – TDMDA
C: Jen-Chieh Wang – CMS/ITRI

**Taiwan Chapter of Photovoltaic
Global Technical Committee**

C: T.C. Wu – CMS/ITRI
C: Ray Sung – UL Taiwan
C: C.C. Lin – PV Guider

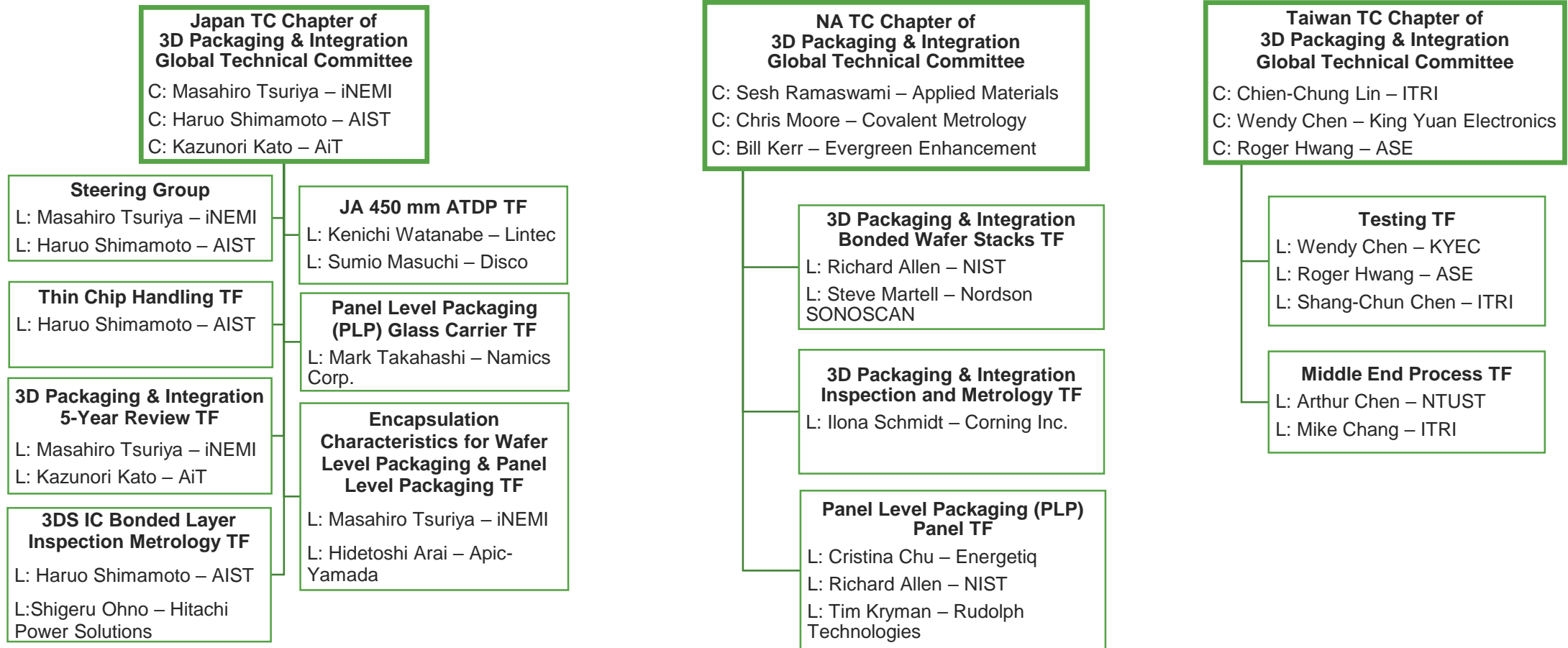
ISC Taiwan Member

Jen-Chieh Wang – CMS/ITR

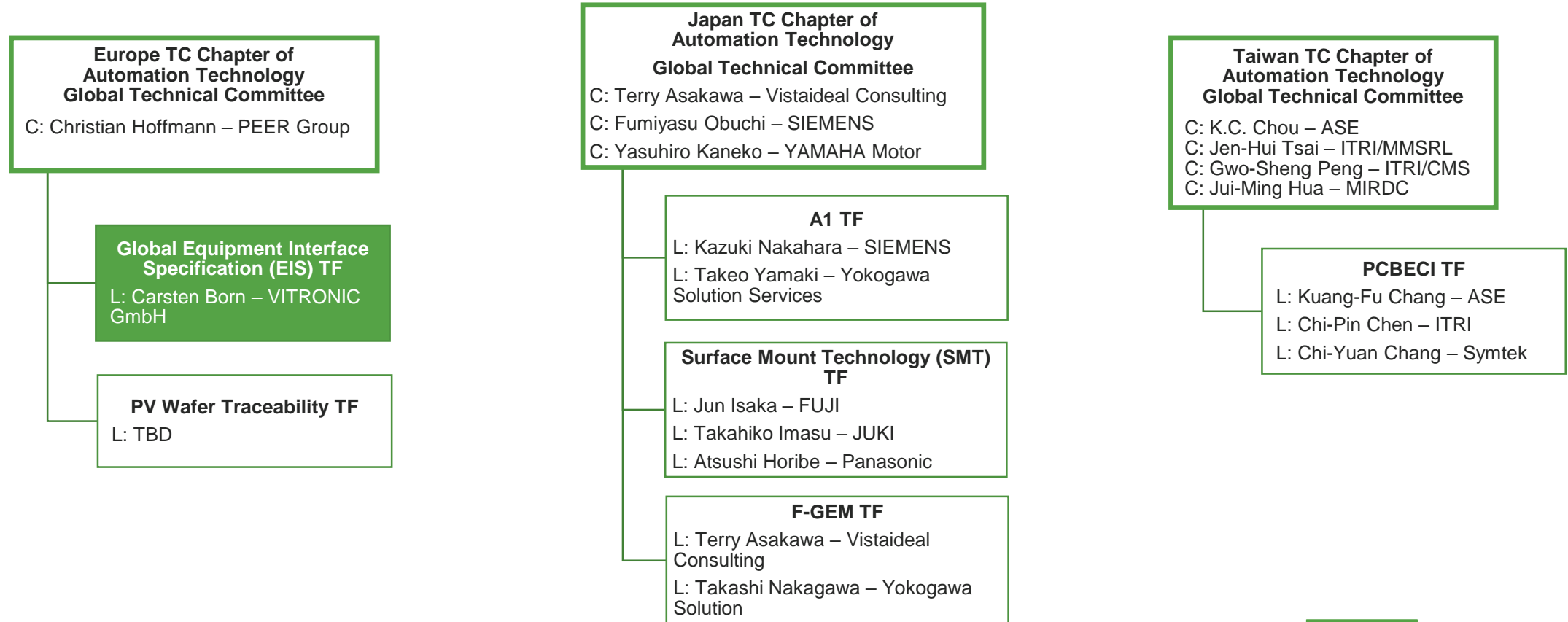
Organization of Each TC Chapter

TF = Task Force | WG = Working Group

3D Packaging & Integration (3DP&I) Global Technical Committee



Automation Technology (AT) Global Technical Committee



 = Global Task Force

Automated Test Equipment (ATE) Global Technical Committee

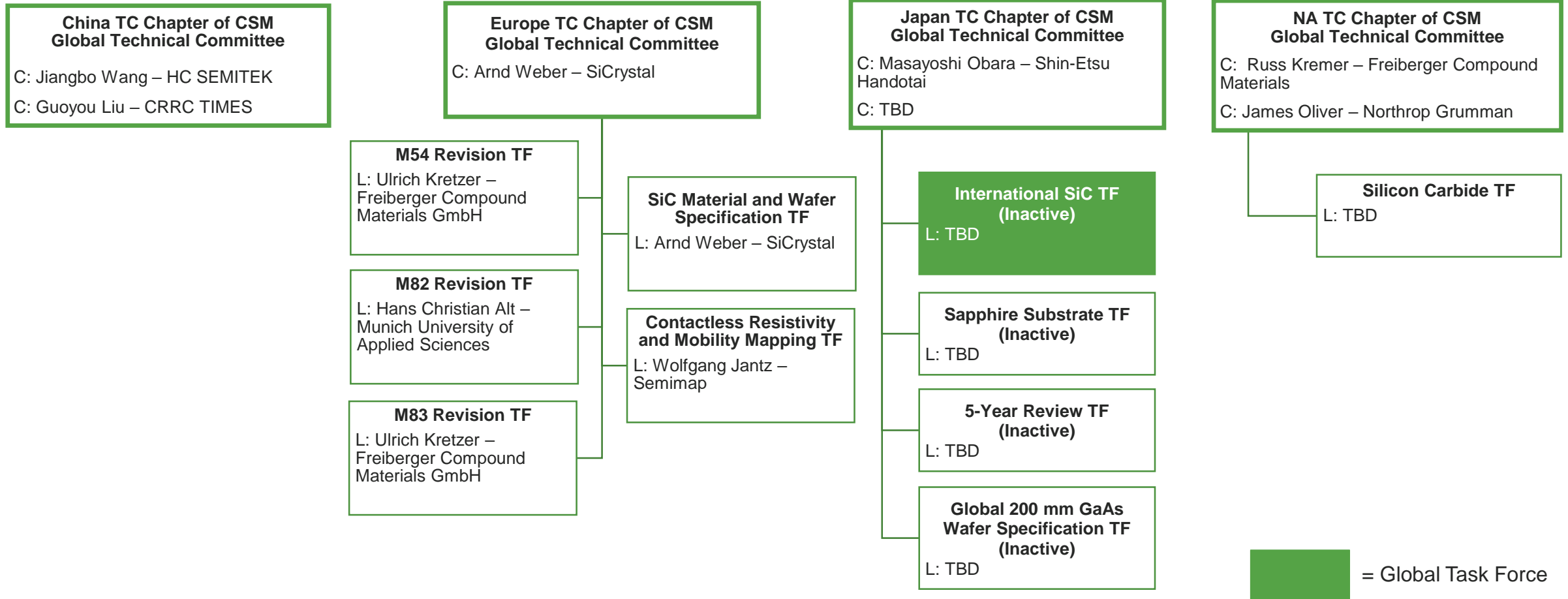


**NA TC Chapter of
Automated Test Equipment
Global Technical Committee**
C: Mark Roos – Roos Instruments
C: Stacey Ajouri – Texas Instruments
C: Laurent Bonneval – Teradyne

Rich Interactive Database (RITdb) TF
L: Mark Roos – Roos Instruments
L: Stacey Ajouri – Texas Instruments

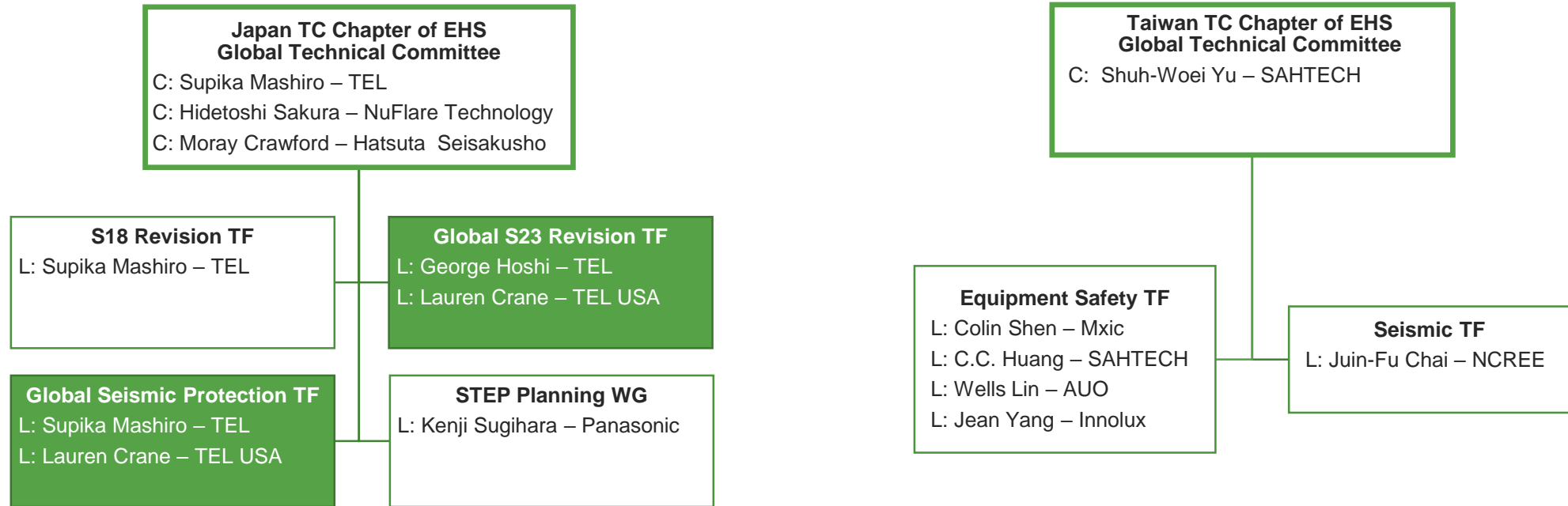
**Tester Event Messaging for
Semiconductors (TEMS) TF**
L: Laurent Bonneval – Teradyne

Compound Semiconductor Materials (CSM) Global Technical Committee



Environmental, Health & Safety (EH&S)

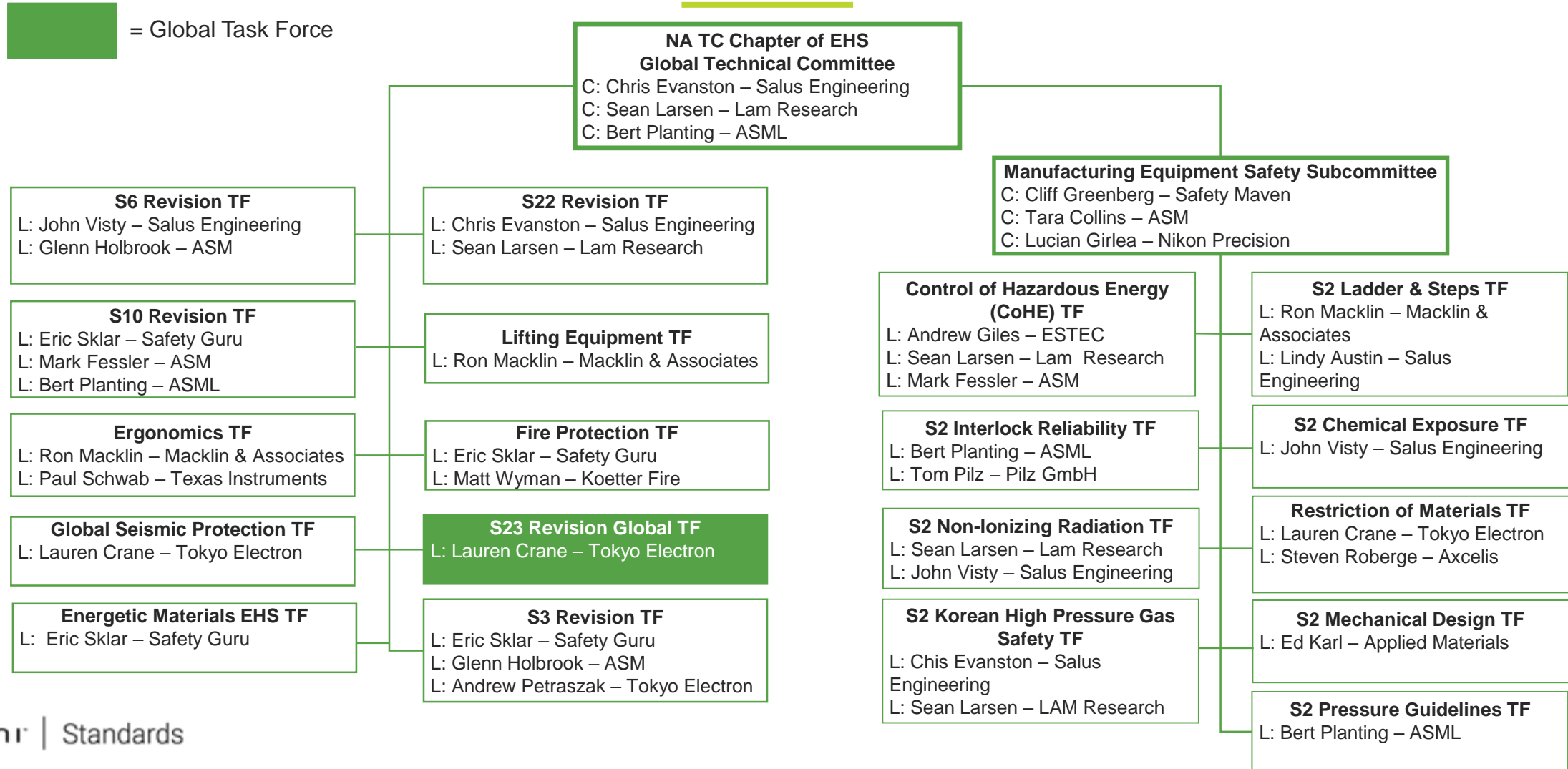
Global Technical Committee



 = Global Task Force

Environmental, Health & Safety (EH&S)

Global Technical Committee



Facilities

Global Technical Committee

**Japan TC Chapter of Facilities
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

F1 Revision TF
L: Masafumi Kitano – Fujikin
L: Kazuhiko Takamisawa –
NISSAN TANAKA

5-Year Review TF
L: Masafumi Kitano – Fujikin

**NA TC Chapter of Facilities
Global Technical Committee**
C: Steve Lewis – BW Design Group

F51 Revision TF
L: Dalia Vernikovsky – Applied
Seals North America

**Building Information Modeling
(BIM) for Semiconductor Capital
Equipment TF**
L: Michael Potts – Exyte

Power Grid Harmonics TF
L: Open

Voltage Sag Immunity TF
L: Mark Stephens – EPRI

**Korea TC Chapter of Facilities
Global Technical Committee**
C: Kwang Sun Kim – KUT

Equipment Cleanness TF
L: TBD

FPD Metrology

Global Technical Committee



**Japan TC Chapter of FPD Metrology
Global Technical Committee**
C: Ryoichi Watanabe – Japan Display
C: Akira Kawaguchi – Otsuka Electronics

**Korea TC Chapter of FPD Metrology
Global Technical Committee**
C: Jongho Chong – Samsung Display
C: Kyungjin Kang – LG Electronics

**Taiwan TC Chapter of FPD Metrology
Global Technical Committee**
C: Jia-Ming Liu – TDMDA
C: Jen-Chieh Wang – CMS/ITRI

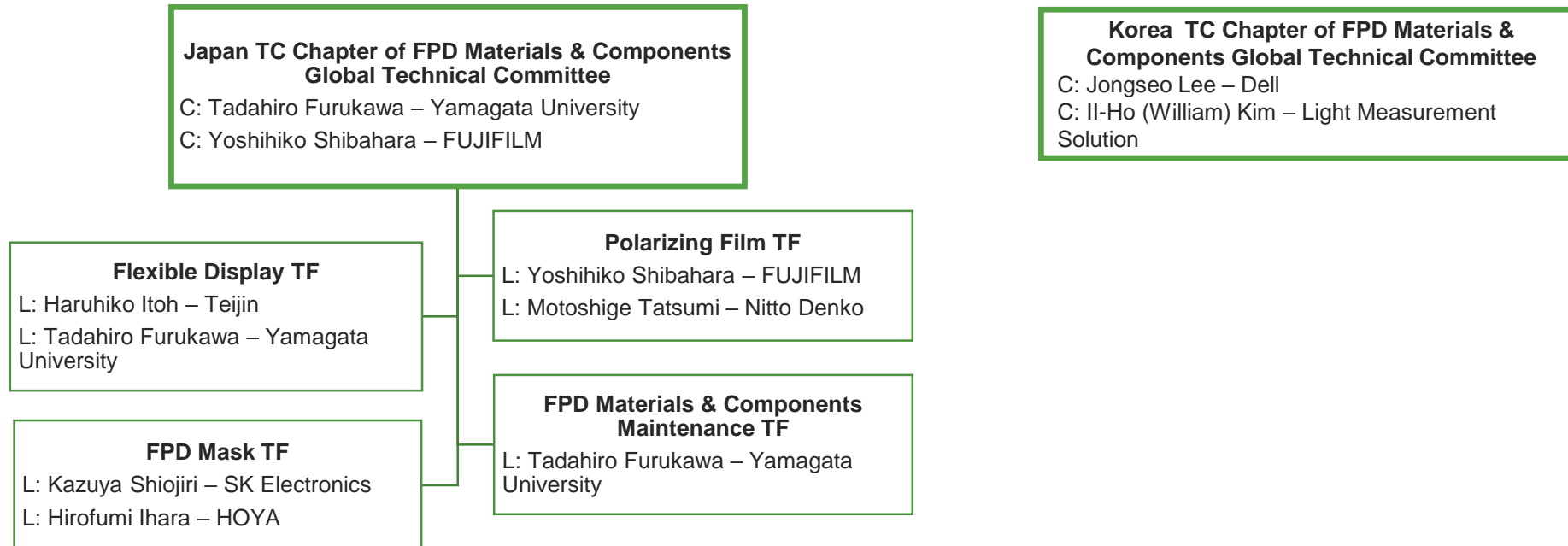
Perceptual Viewing Angle TF
L: Myoungyoung Lee – LG Electronics

Perceptual Image Quality TF
L: Jongho Chong – Samsung Display

Flexible Display TF
L: Chao-Hua Wen – ITRI

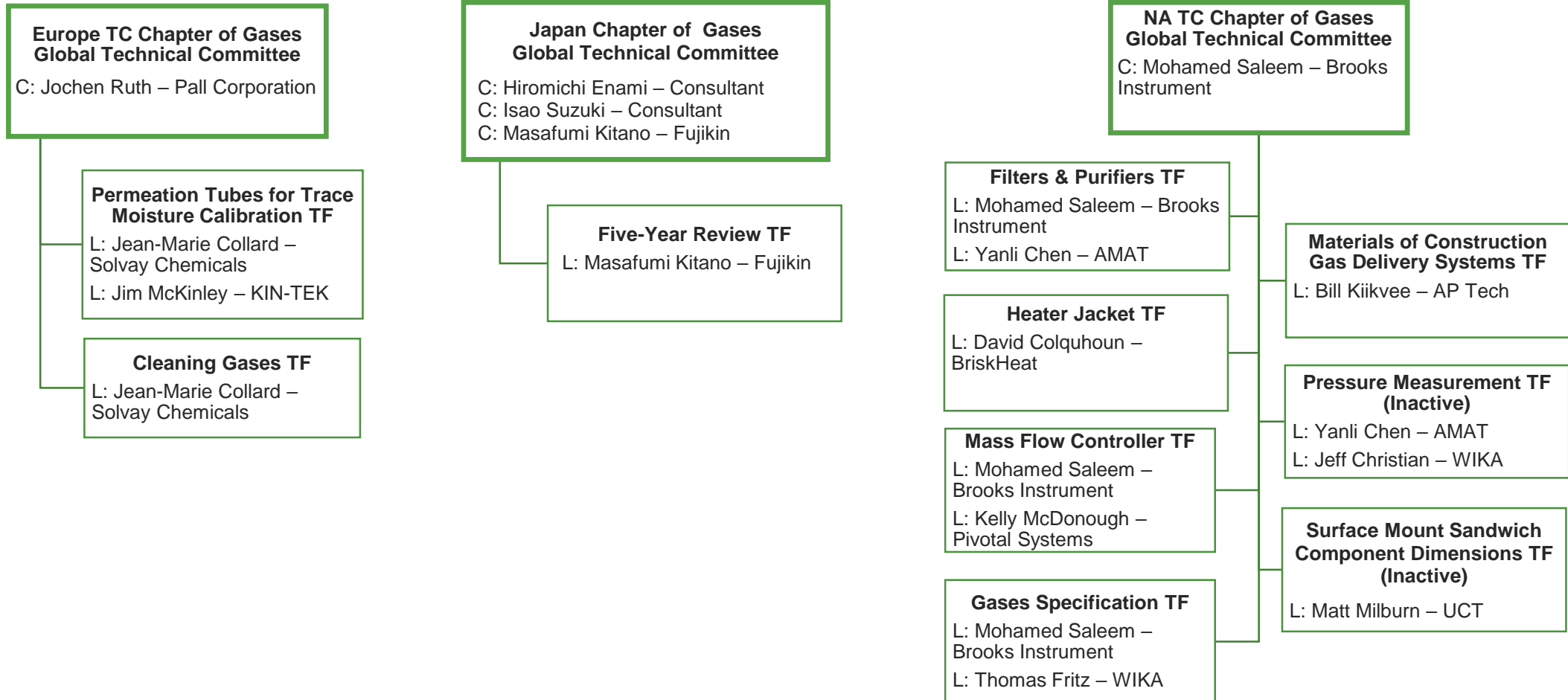
Transparent Display TF
L: Pei-Li Sun – NTUST
L: Justic Lin – Acer

FPD Materials & Components Global Technical Committee



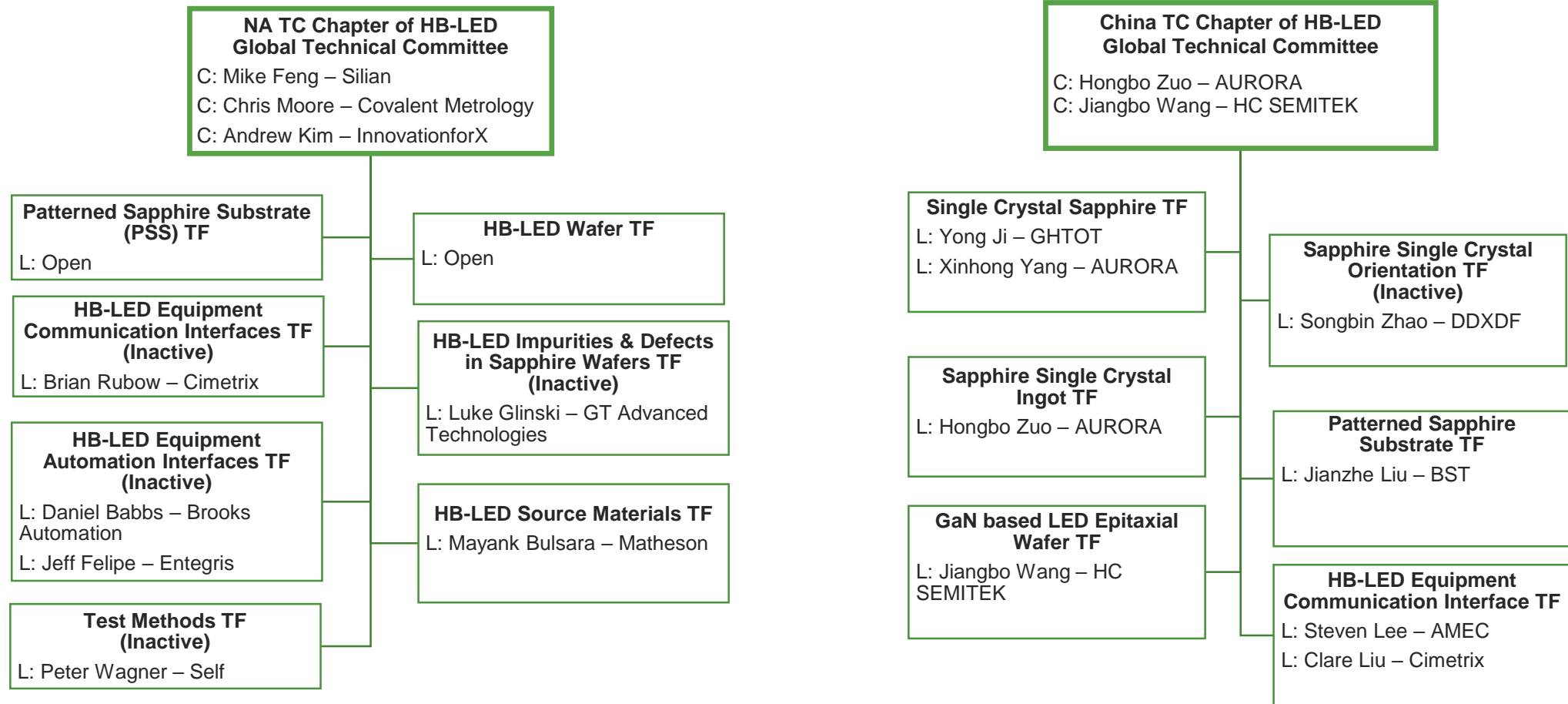
Gases

Global Technical Committee

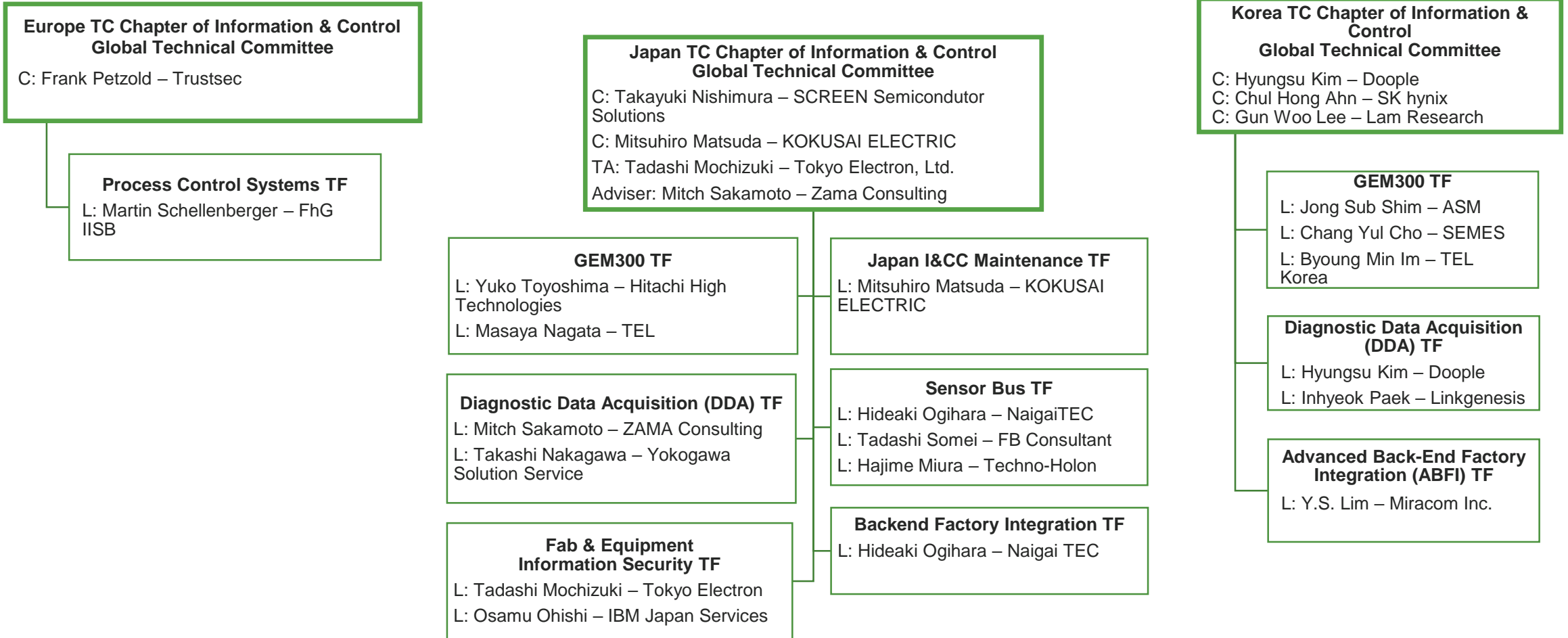


HB-LED

Global Technical Committee

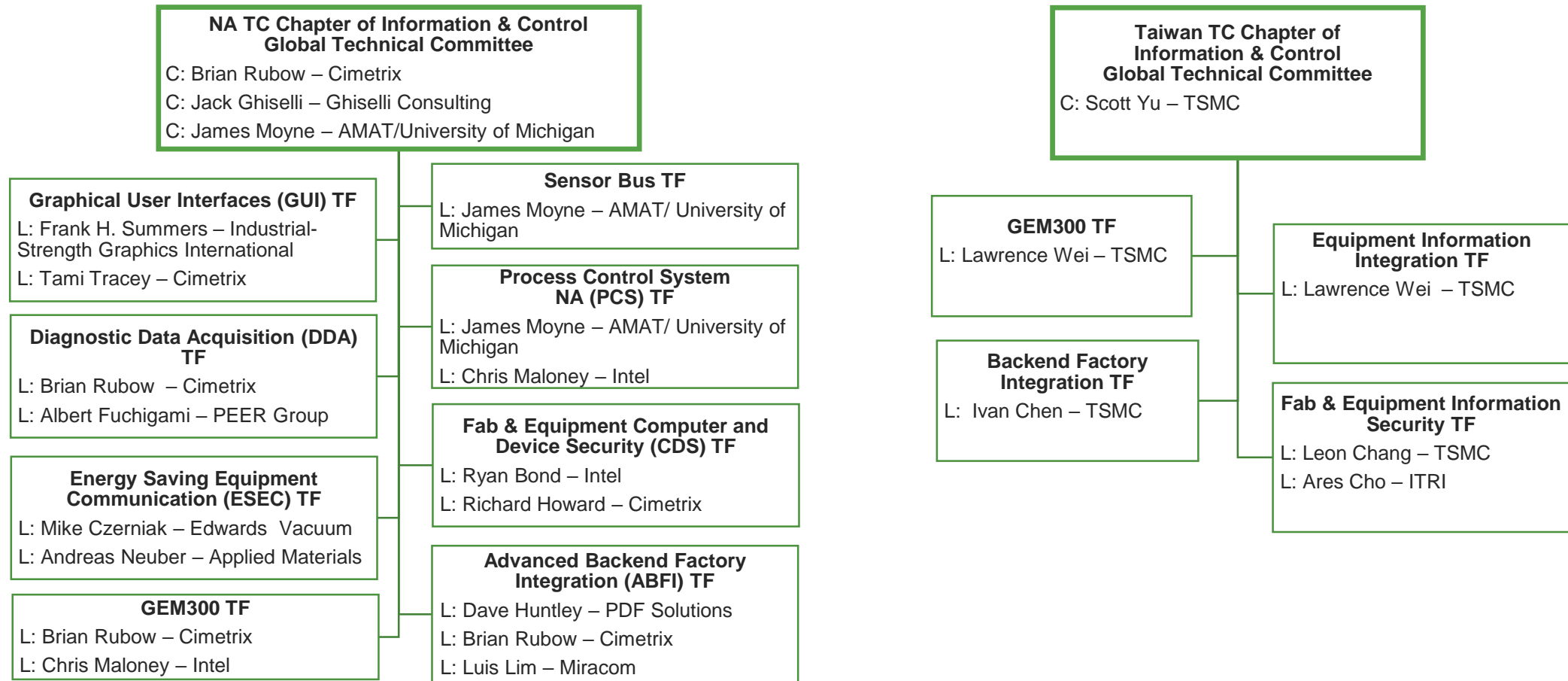


Information & Control (I&C) Global Technical Committee



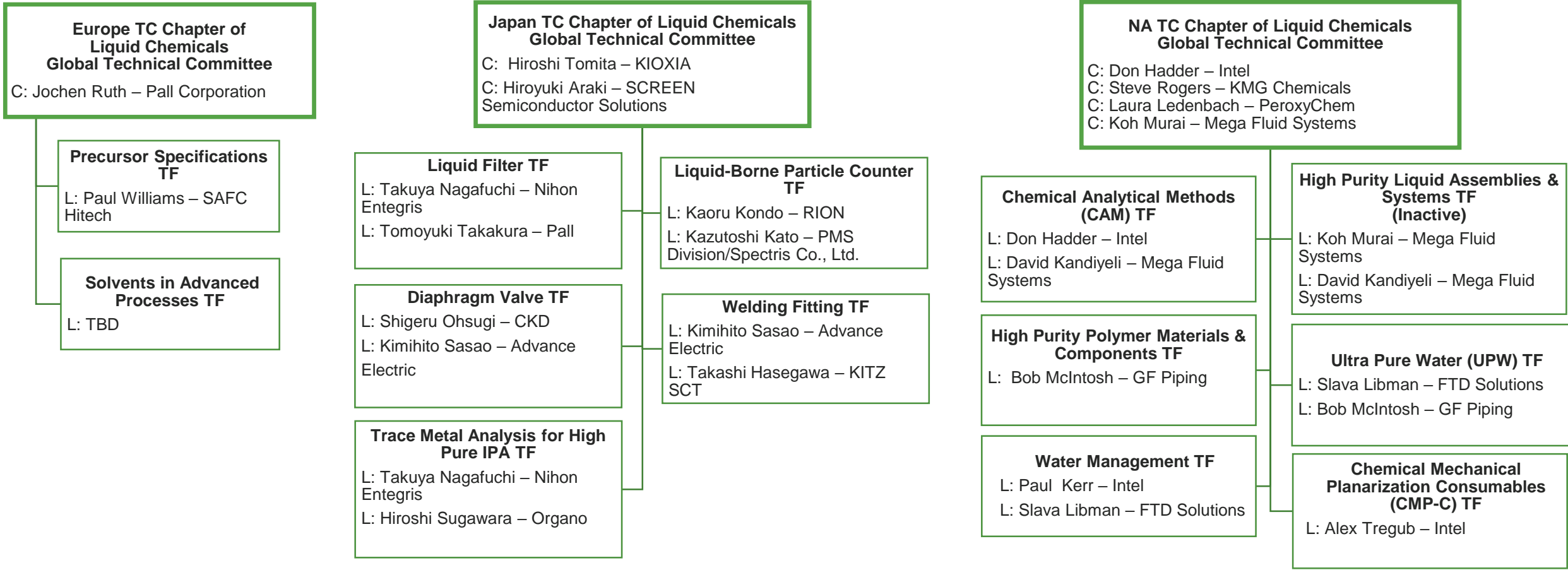
Information & Control (I&C)

Global Technical Communities



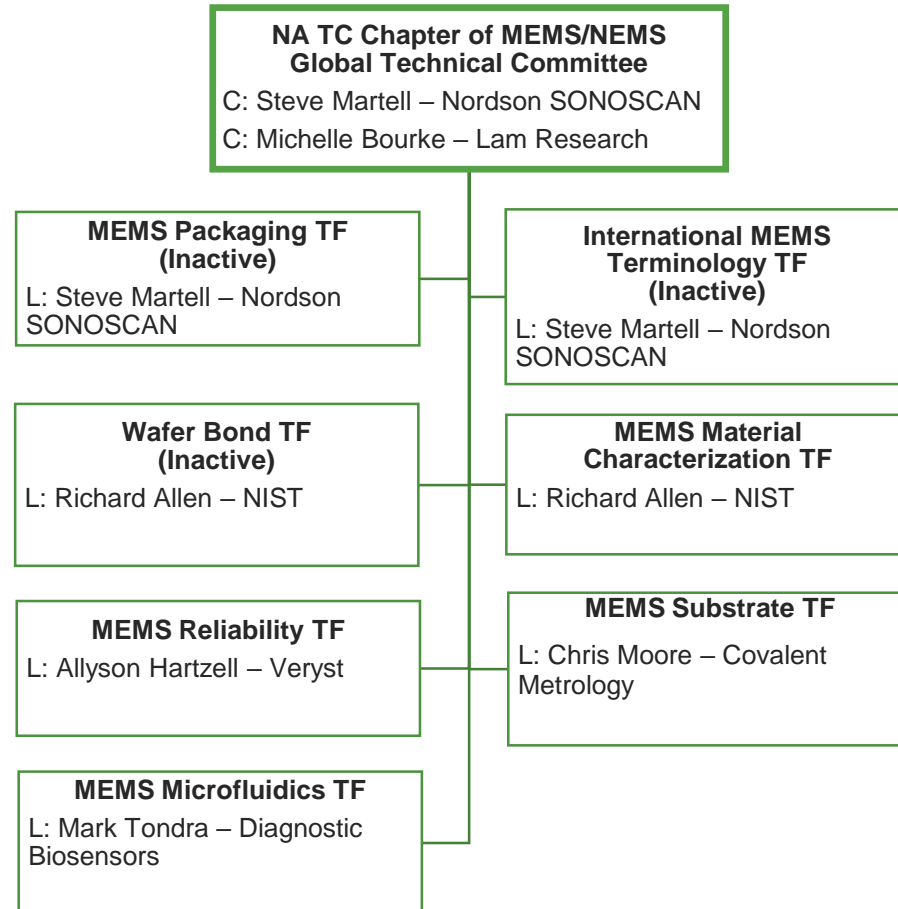
Liquid Chemicals

Global Technical Committee



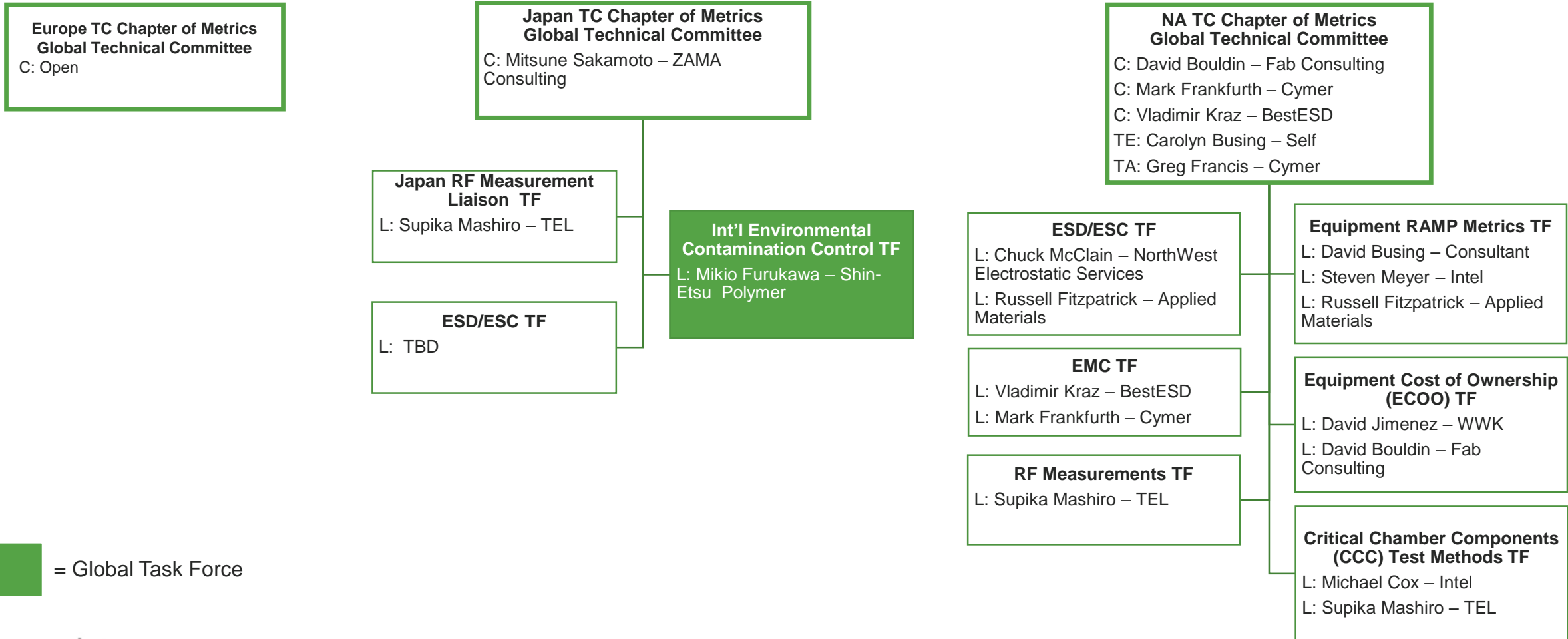
MEMS/NEMS

Global Technical Committee



Metrics

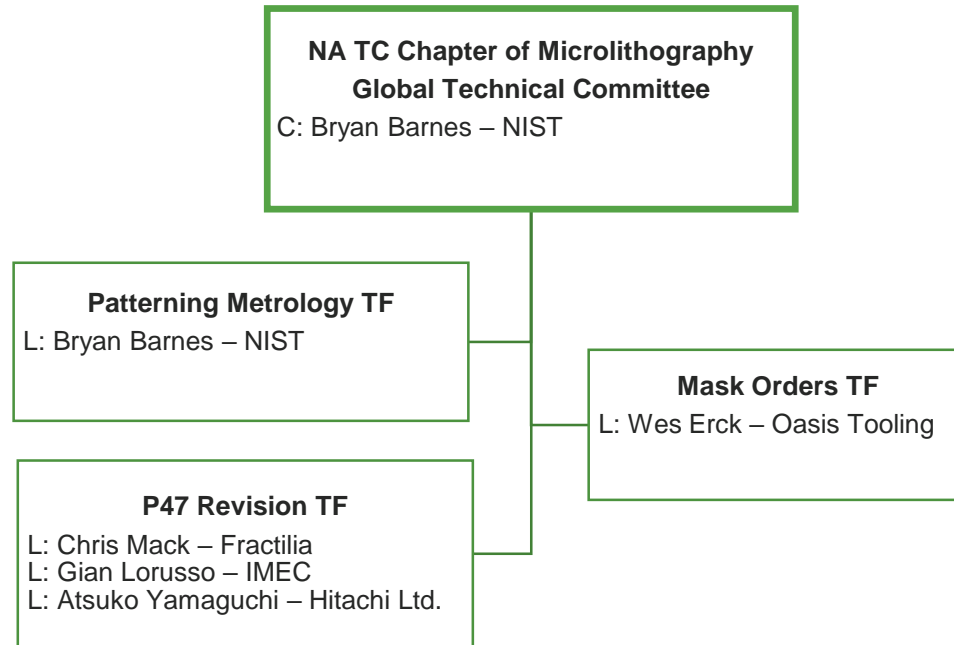
Global Technical Committee



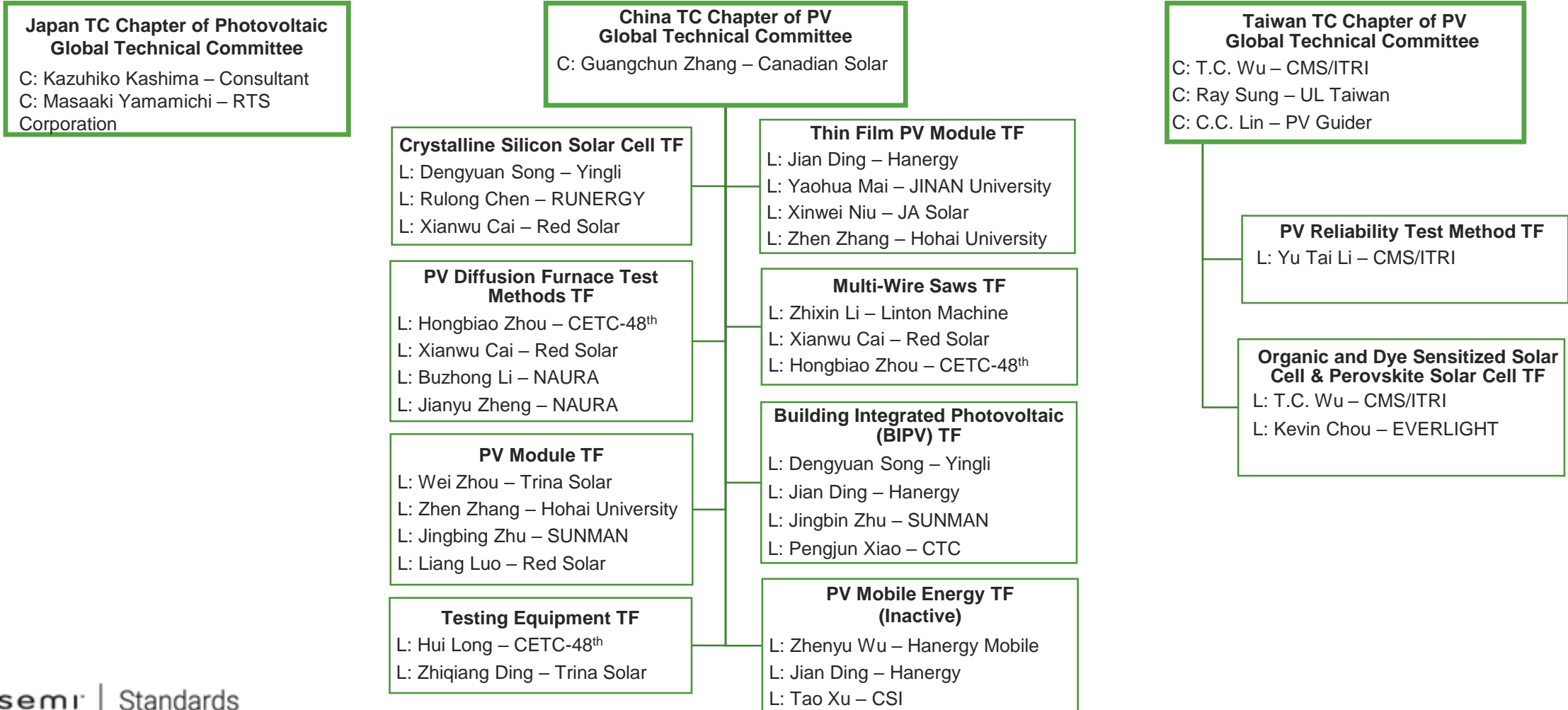
 = Global Task Force

Micropatterning

Global Technical Committee

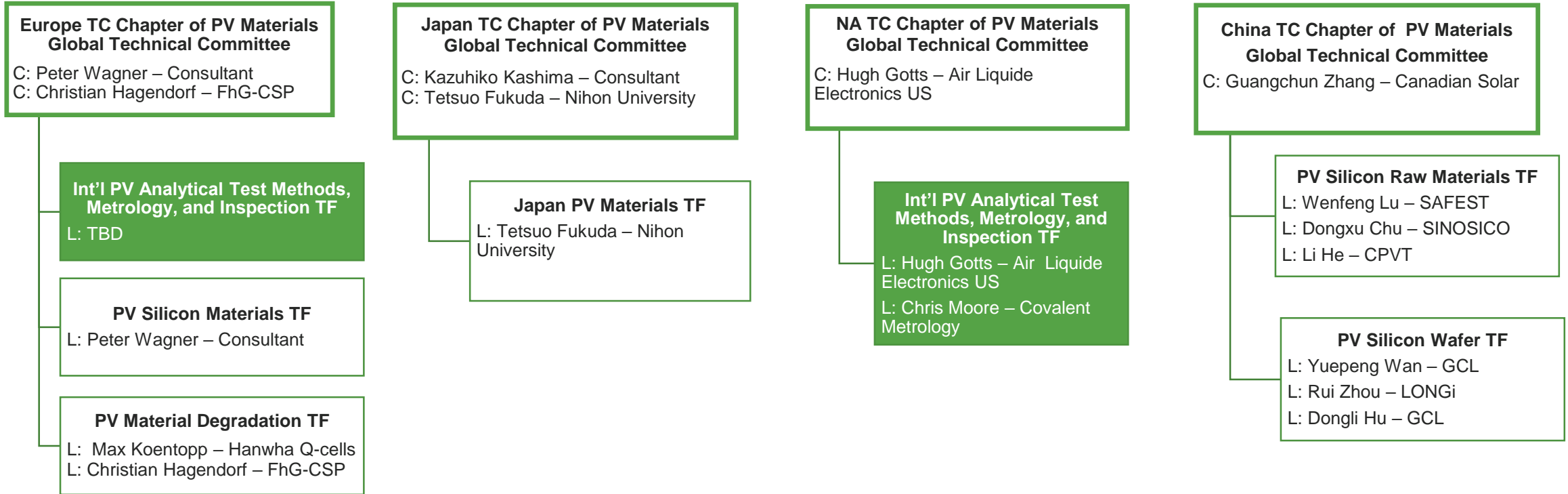



Photovoltaic (PV) Global Technical Committee



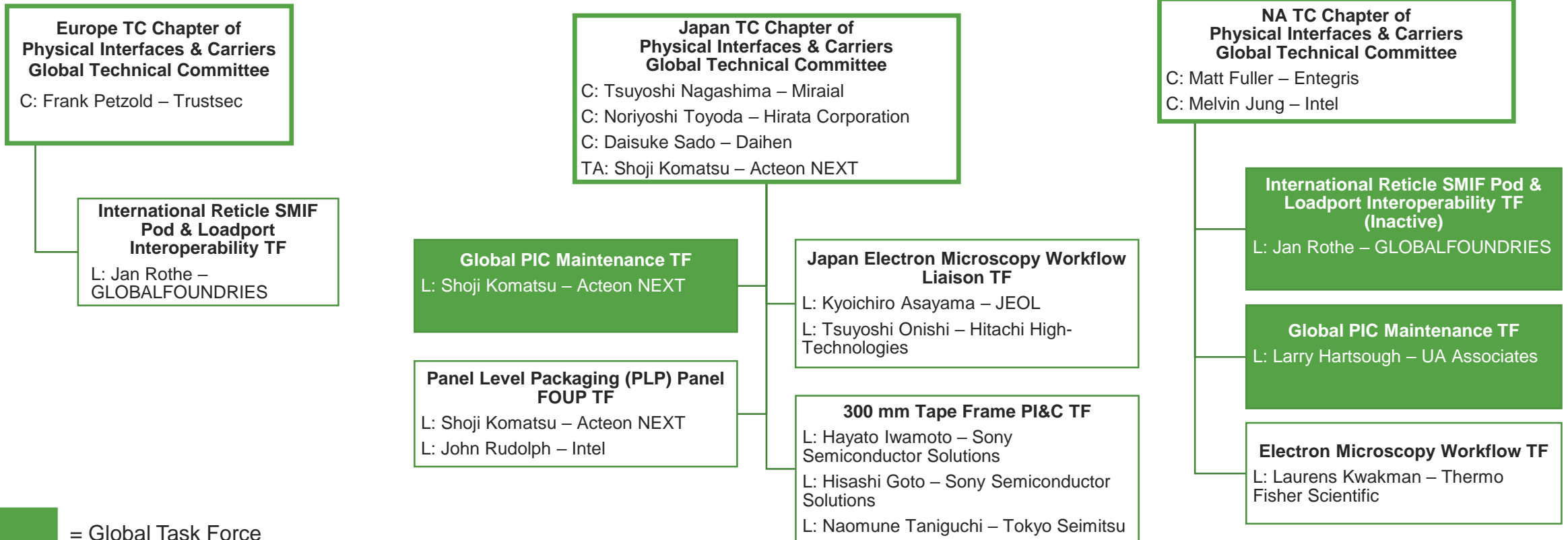
PV Materials

Global Technical Committee



 = Global Task Force

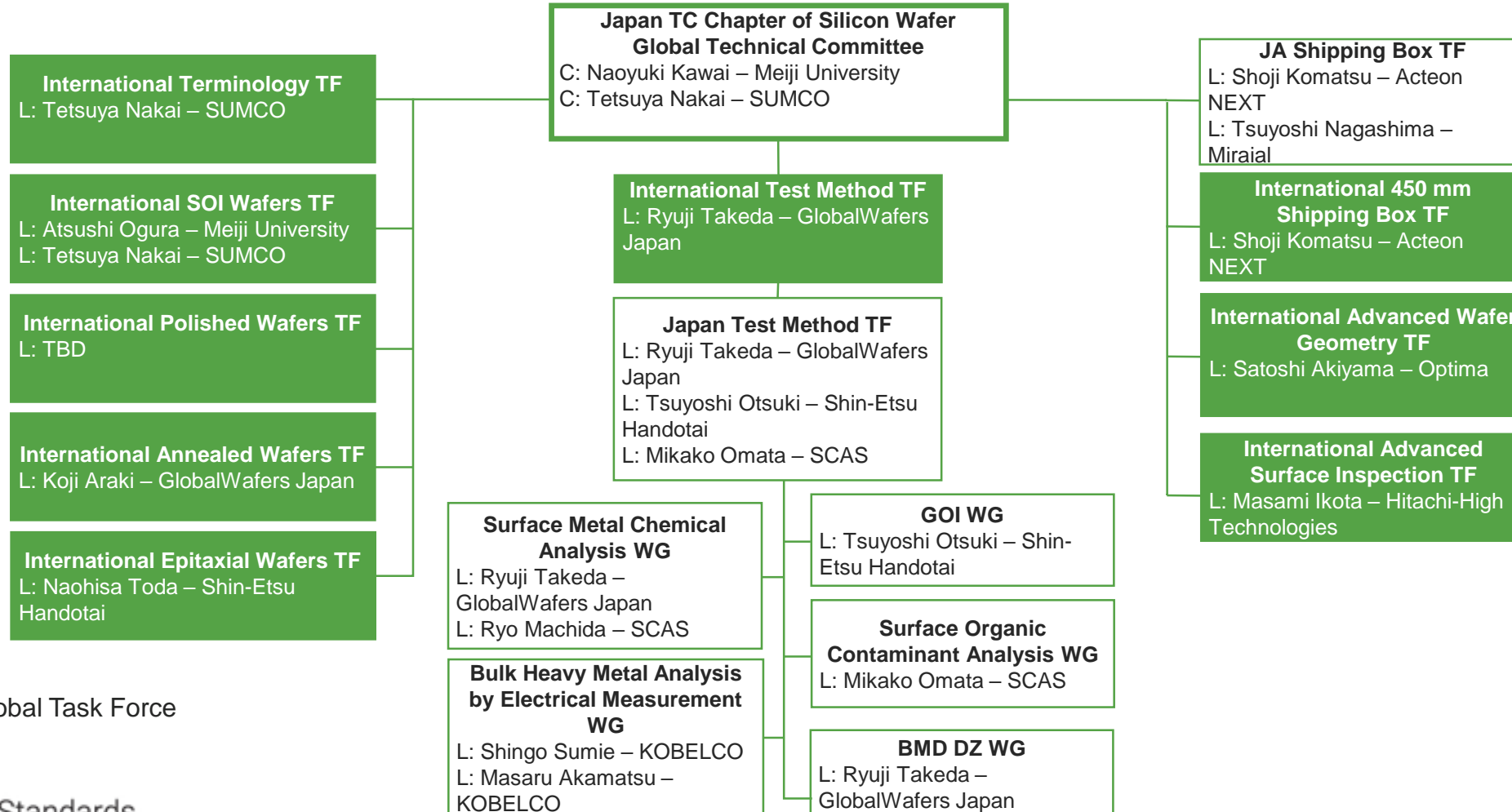
Physical Interfaces & Carriers (PI&C) Global Technical Committee




Silicon Wafer Global Technical Committee



Silicon Wafer Global Technical Committee



 = Global Task Force

Traceability

Global Technical Committee



**Japan TC Chapter of Traceability
Global Technical Committee**
C: Yoichi Iga – JEITA
C: Hirokazu Tsunobuchi – Nidec Sankyo

5-Year Review TF
L: Hirokazu Tsunobuchi – Nidec Sankyo

**Japan Equipment & Materials
Traceability Liaison TF**
L: Yoichi Iga – JEITA
L: Hirokazu Tsunobuchi – Nidec Sankyo

**Japan Single Device
Traceability Liaison TF**
L: Yoichi Iga – JEITA
L: Hirokazu Tsunobuchi – Nidec Sankyo

**NA TC Chapter of Traceability
Global Technical Committee**
C: Yaw Obeng – NIST
C: David Huntley – PDF Solutions

5-Year Review TF
L: Masanori Yoshise – Self

**Equipment and Materials
Traceability TF**
L: Eric Bruce – Samsung
L: Lance Dyrdaahl – Lam Research
L: Jeff Hanan – GlobalFoundries

Single Device Traceability TF
L: Dave Huntley – PDF Solutions
L: Chris Portelli – STMicro
L: Zoe Conroy – Cisco